

TRANSISTORS, MICROWAVE, SMALL SIGNAL, SILICON, BIPOLAR, BASED ON TYPES BFY405, BFY420 AND BFY450 Component Title:

DLR Executive Member: Date: 22/10/2021

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Components (includi	ng series and famil	ies) sı	ubmitted for Ext	tension	of Qualification	Approval:					1
ESCC COMPONENT NO.	VARIANTS	RANGE (	OF COM	MPONENTS	BASED ON			TEST VEHICLE / S	COMPONI SIMILAI		
5611/008	01 to 03					BFY405 BFY420 BFY450			BFY193C(ES)	Y	
Component Manufacturer 2 Infineon Technologies AG			Location of Manufacturing Plant(s)  Villach, Austria and Regensburg, Germany for Silicon  Neubiberg, Germany for packing and screening				Date of original qualification approval: Date: 1997  Certificate Ref No. 245, initial: Juni 1997				
ESCC Specifications used for Maintenance of qualification testing: Generic: 5010 Issue: 3  Detail(s): 5611/006 Issue: 8			Deviations to LVT testing and Detail Specification used:  No ⊠ Yes □ (supply details in Box 15)  Deviation from current Specifications:  No ⊠ Yes □ (Supply details)					Qualification Extension Report reference and date: 2013LR80, lss. 1, Aug. 2021			
Summary of procurement or equivalent test r Project Name Testing Level			esults during current validity period in support of LAT Date co			ipport of th	nis app	olication	`	irst) Delivered	8
PID changes since s	tart of qualification			9	Current PID \	/erified by:			B. Gökgöz, DLR		10
None   Name of Excutive Representative  Minor*   Generic PID: A63500-GEPID-P000, Issue 2f, 13.10.2021 Detail PID: A63500-T503-P000, Issue 4, 16.10.2019  Major*   *Provide details in box:  See Annex 2											
(Name					R (B. Gökgöz, T. e of Executive Re		ve)	on		:/10/2021 (Date)	11
Report Reference:	Infineon_Mo0 _1.5	Q_202	21_MoM_Rev_	_							



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Failure Analysis, DPA, NCCS a	vailable:	Yes		No		(Supply data)				12
						( 11 ) /				
Ref. No's and purposes:										ı
The undersigned hereby certifies on behind that the appropriate documentation has been (except as stated in box 15;) - that the re	een evaluated	; - that full	complia	ance to	all ESC	C requirements i	s eviden	ce s on behalf of		13
DLR as the responsible Executive Memb	er for ESCC qu	ualification	status	to be ex	tended	to the componer	nt(s) liste	d herein.		
								Blook gi	aliges	
Date: 17/11/2021								B. Gökgöz	0	_
Continuation of Doves shows							(8	ignature of the Executive	Coordinator)	T 44
Continuation of Boxes above:										14



Component title:

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Date: 22/10/2021 Executive Member:

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Non compliance to ESCC requirements:

No.:	Specification	Paragraph	Non compliance	
Additiona noncomp	Il tasks required to achieve full compliance for I liance:	ESCC qualification or rationale for acceptability	of	16
Executive	e Manager Disposition			47
				17
Action / R	on Approval: Yes ⊠ No □ Remarks:			
			Britta Digitally signed by Britta Schade	
			Cabada Date: 2021.12.20	
Date:				
ſ			B. Schade: Head of the Product Assurance and Safety Department	



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ANNEX 1: LIST OF TESTS DONE TO SUPPORT EXTENSION OF QUALIFICATION

Tests conducted in compliance with:

ESCC 5010 generic specification; Chart V (for ESCC/QPL parts)

Tests vehicle identification/description:

2013LR80, 2010A  ${\tt BFY193C(ES),\,EnvMechSG,\,EndSG,\,AssCapSG,\,DecapSG}$ 

Detail Specification reference: 5611/006

Chart F4A	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
Environmental/Mechanical Subgroups	Thermal Shock Test	$\boxtimes$	ESCC 5010 Para. 9.5.2	2010A	11	0	
	Shock Test		MIL-STD-750 Test Method 2016				n.a. acc. Detail Spec
	Vibration Test		MIL-STD-750 Test Method 2056				n.a. acc. Detail Spec
	Constant Acceleration		MIL-STD-750 Test Method 2006				n.a. acc. Detail Spec
chanic	Seal Test		MIL-STD-750 Test Method 1071				n.a. acc. Detail Spec
al/Med	Moisture Resistance	$\boxtimes$	MIL-STD-750 Test Method 1021	2010A	11	0	
nment	Seal Test	$\boxtimes$	MIL-STD-750 Test Method 1071	2010A	11	0	
Enviro	Electrical Measurements at Room Temp.		Table 2 of the Detail Specification	2010A	11	0	
	External Visual Inspection	$\boxtimes$	ESCC Basic Specification No. 20500	2010A	11	0	
Endurance Subgroup	Operating Life	$\boxtimes$	MIL-STD-750 Test Method 1026	2010A	16	0	
	Electrical Measurements during Endur. Test	$\boxtimes$	Table 6 of the Detail Specification	2010A	16	0	
	External Visual Inspection	$\boxtimes$	ESCC Basic Specification No. 20500	2010A	16	0	
group ly ests	Solderability Test		MIL-STD-750 Test Method 2026	2010A	5	0	
Electrical Subgroup  - Assembly Capability Tests	Permanence of Marking		ESCC Basic Specification No. 24800				n.a. due to laser marking
	Terminal Strength		MIL-STD-750 Test Method 2036	2010A	5	0	
De- encapsulation Tests	Internal visual inspection		ESCC Basic Specification No. 20400	2010A	6	0	
	Bond Strength	$\boxtimes$	MIL-STD-750 Test Method 2037	2010A	6	0	
en	Die Shear	$\boxtimes$	MIL-STD-750 Test Method 2017	2010A	6	0	



Box 22

Additional Comments.

### APPLICATION FOR EXTENSION OF ESCC QUALIFICATION APPROVAL

TRANSISTORS, MICROWAVE, SMALL SIGNAL, SILICON, BIPOLAR, BASED ON TYPES BFY405, BFY420 AND BFY450 Component title:

Executive Member: Date: 22/10/2021

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# NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL

	NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL
<b>ENTRIES</b> Form heading	shall indicate: - the title of the component as given in its detail specification or the name of the series, family; - the Executive Member; - the entering date; - the certificate number and its sequential suffix.
Box 1	shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of components (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given in the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable of identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.
Box 2; 3 and 4	As per QPL entry; otherwise, an explanation of the changes must be supplied.
Box 5	Will show the ESCC Generic and Detail specifications, including issue number and revision letter, current at the time the tests reported were performed. If the specifications are different from those current on the date of the application, see Box 6.
Box 6	Will show the deviations from the Generic and Detail Specifications listed in Box 5, in particular deviations from testing. In case of deviations this must be listed in Box 15. In case the referenced specification in Box 5 have currently a different issue and/or revision indicate also whether the test data deviates or not from such current documents.
Box 7	Must reference the report(s) supplied in support of the application.
Box 8	Should provide the details of procurement to the full ESCC System, documentation of all of which should already have been delivered to the ESCC Executive under the terms of the relevant Generic Specification. An appropriate table has been drawn in this box.
Box 9	If the PID evolved after the Original Qualification or after the last Extension of Qualification, adequate details of such evolution shall be provided together with the reasons for the changes. Major changes shall be clearly marked.
Box 10	Identify the current PID issue status, date and actual date of verification. The date of verification of the current PID should be arranged as close as possible to the required date of extension.
Box 11	This box can be completed only after a physical visit to the plant to confirm that no unexplained changes occurred and that the practices, procedures, material, etc. used in manufacturing the components are as described in the PID. This survey shall be carried out in accordance with the requirements of ESCC Basic Specification No. 20200 and its findings shall be recorded.
Box 12	Provide details of, or reference to, any Destructive Physical Analysis (DPA) and Failure Analysis reports as well as any Nonconformance(s) (NCCS) occurred during the qualification validity period, stating if established corrective action have produced satisfactory results.
Box 13	Enter only the name of the Executive Member (i.e., CNES, DLR, ESTEC, etc.) and the signature of the responsible Executive Coordinator.
Box 14	To be used when there is a need to expand any of the boxes from 1 through 12. Identify box affected and reference the Box 14 in the relevant Box. Box 14 can be broken into 14a, 14b, etc. if several boxes have to be expanded.
Box 15	Fill in Table as requested.
Box 16	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 17	All Executive Manager recommendations on the application itself, special conditions or restrictions, modifications of the QPL or QML entry, letters to the manufacturer, etc. shall be entered clearly in Box 19, signed by the representative for ESA, and dated.
Box 18	Fill in Table as requested.
Box 19	Confidential Details of PID changes including those of a confidential nature, shall be provided.
Box 20	State noncompliance with reference to specification(s) and paragraph(s). To simplify reference in Box 16 each nonconformance shall be sequentially numbered. If relevant state 'None'.
Box 21	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.